PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Kwan-Yong Lim	06/10/2011
Chung-Geun Koh	05/27/2011
Sang-Bom Kang	05/27/2011
Ui-Hui Kwon	05/27/2011
Hyun-Jung Lee	05/27/2011
Tae-Ouk Kwon	05/27/2011
Seok-Hoon Kim	05/27/2011

RECEIVING PARTY DATA

Name:	Samsung Electronics Co., Ltd.
Street Address:	416, Maetan-dong, Yeongtong-gu
City:	Suwon-si, Gyeonggi-do
State/Country:	REPUBLIC OF KOREA

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13240470

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER: SAM-1537

PATENT REEL: 026950 FRAME: 0420 DP \$40.00 13240470

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NAME OF SUBMITTER:	Anthony P. Onello, Jr.
Total Attachments: 4 source=1537_assignasfiled#page1.tif source=1537_assignasfiled#page2.tif source=1537_assignasfiled#page3.tif source=1537_assignasfiled#page4.tif	

PATENT REEL: 026950 FRAME: 0421

ASSIGNMENT

We, Kwan-Yong Lim, of #139-702 Park town Daerim Apt., Sunae-dong, Bundang-gu, Seongnam-si, Gyeonggi-do, Republic of Korea, Chung-Geun Koh, of #907-1104 Godeok Jugong Apt., Myeongil-dong, Gangdong-gu, Seoul, Republic of Korea, Sang-Bom Kang, of #111-504 Banpo Apt., 919 Banpo-dong, Seocho-gu, Seoul, Republic of Korea, Ui-Hui Kwon, of #349-1406 Sibeom Daeun Maeul Unam Firstvill Apt., Bangsong-dong, Hwaseong-si, Gyeonggi-do, Republic of Korea, Hyun-Jung Lee, of #F-1002 Digital Empire Bldg., 980-3 Yeongtong-dong, Yeongtong-gu, Suwon-si, Gyeonggi-do, Republic of Korea, Tae-Ouk Kwon, of #402 Jinan Building, 879-2 Jinan-dong, Hwaseong-si, Gyeonggi-do, Republic of Korea; and Seok-Hoon Kim, of #301-602 Bandal Maeul Purgio Apt., Banwol-dong, Hwaseong-si, Gyeonggi-do, Republic of Korea; having invented improvements in METHOD FOR MANUFACTURING SEMICONDUCTOR DEVICE identified as Attorney Docket No. SAM-1537, described in an application for Letters Patent of the United States, which application was filed on September 22, 2011, and assigned Serial No. 13/240,470 (in the event that the execution date, filing date and/or Serial No. are not entered above at the time we execute this document, and if such information is deemed necessary, we hereby authorize and request our attorneys at Mills & Onello, LLP, Eleven Beacon Street, Suite 605, Boston, Massachusetts 02108, USA, to insert above the execution date, filing date and/or Serial No. of said application, when known), for good and valuable consideration, receipt of which is hereby acknowledged from Samsung Electronics Co., Ltd., a Korean corporation having a place of business at 416, Maetan-dong, Yeongtong-gu, Suwon-si, Gyeonggi-do, Republic of Korea (and hereinafter called the Assignee, which term shall include its successors and assigns), do hereby sell, assign and transfer unto the Assignee our entire right, title, and interest in and throughout the United States of America (including its territories and dependencies) and all countries foreign thereto, in and to and under said application (which term shall include hereinafter where the context so admits all divisional, continuing, reissue and other patent applications based thereon) and the inventions (which term shall include each and every such invention, or part thereof) therein described, and any and all patents and like rights of exclusion (including extensions thereof) of any country which may be granted on or for said inventions or on said application;

And for the same consideration We do also hereby sell, assign, and transfer unto the Assignee, all our rights under the International Convention for the Protection of Industrial Property, the Patent Cooperation Treaty, and all other treaties of like purpose in respect of said inventions and said application, and We do hereby authorize the Assignee to apply in our name or its own name or its designee for patents and like rights of exclusion on or for said inventions in all countries, claiming (if the Assignee so desires) the priority of the filing date of said application under the provisions of said Convention, Treaty or any such other Convention or Treaty;

And for the same consideration, We do hereby agree for ourselves and for our heirs, executors, and administrators, promptly upon request of the Assignee to execute and deliver without further compensation any power of attorney, assignment, original, divisional, continuing, reissue or other application or applications for patents or like rights of exclusion of any country, or other lawful documents and any further assurances that may be deemed necessary or desirable by the Assignee, fully to secure to it said right, title, and interest as aforesaid in and to said inventions, applications, and said several patents and like rights of exclusion (including extensions thereof) or any of them, all, however, at the expense of the Assignee, its successors, or assigns;

And We do hereby authorize and request the Commissioner of Patents and Trademarks of the United States of America and the corresponding Official of each country foreign thereto to issue to the Assignee, any and all patents and like rights of exclusion which may be granted in any country upon said United States application on or for said inventions;

And We do hereby covenant for ourselves and our legal representatives and agree with the Assignee, that We have granted no right or license to make, use, or sell said inventions to anyone except the Assignee, that prior to the execution of this deed our right, title, and interest in and to said inventions has not been otherwise encumbered by us, and that We have not executed and will not execute any instruments in conflict herewith.

First or Sole Invent	or:	
Signature:	Kwan-Yong Lim	Date: <u>Jun 10, 201</u>
Second Joint Invent	ior:	
Signature:	Chung-Geun Koh	Date:
Third Joint Inventor	r;-	
Signature:	Sang-Bom Kang	Date:
Fourth Joint Invente	or:	
Signature:	Ui-Hui Kwon	Date:

And We do hereby authorize and request the Commissioner of Patents and Trademarks of the United States of America and the corresponding Official of each country foreign thereto to issue to the Assignee, any and all patents and like rights of exclusion which may be granted in any country upon said United States application on or for said inventions;

And We do hereby covenant for ourselves and our legal representatives and agree with the Assignee, that We have granted no right or license to make, use, or sell said inventions to anyone except the Assignee, that prior to the execution of this deed our right, title, and interest in and to said inventions has not been otherwise encumbered by us, and that We have not executed and will not execute any instruments in conflict herewith.

First or Sole Invente	or:	
Signature:	Kwan-Yong Lim	Date:
Second Joint Inventories Signature:	Chung Geun Coh Chung-Geun Koh	Date: <u>May 27, 2011</u>
Third Joint Invento Signature:	Sang-Bom Kang	Date: May 27, 2011
Fourth Joint Invent	or:	
Signature:	Kwon Wi huj Ui-Hui Kwon	Date: May, 27, 201/

Fifth Joint Inventor:

Signature:

Date: May 27, 2011.

Sixth Joint Inventor:

Signature:

Tae-Ouk Kwon Date: May 27. 2011

Seventh Joint Inventor:

Scokhan Cin Date: May 27, 20/1

ATTORNEY REFERENCE NO.: SAM-1537 JASAM/1537/1537_ASSIGNMENT.DOC

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